

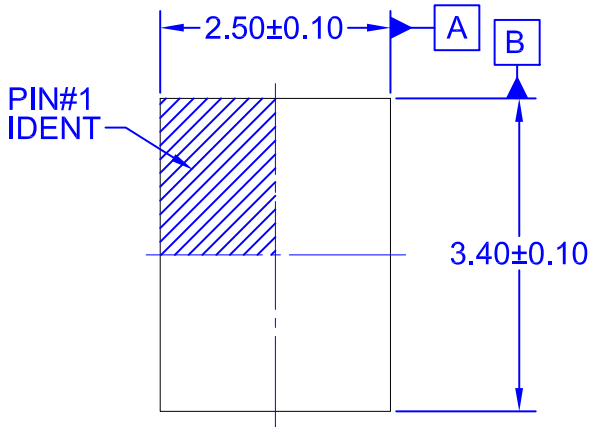
**MECHANICAL CASE OUTLINE**  
**PACKAGE DIMENSIONS**

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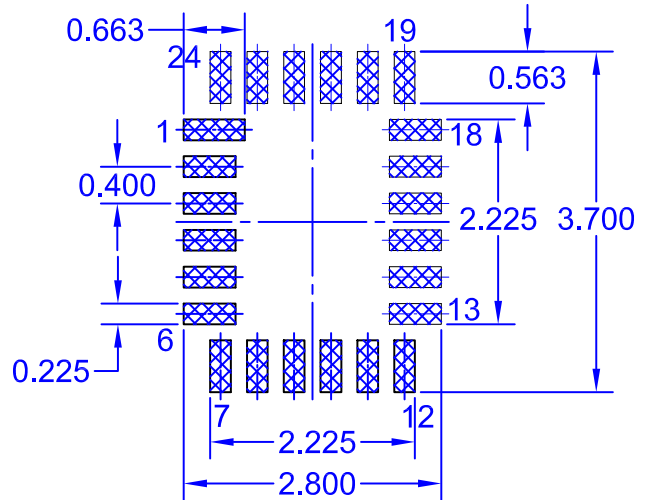


**UQFN24 2.5x3.4, 0.4P**  
CASE 523AX  
ISSUE A

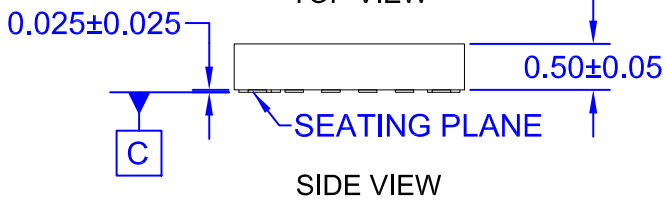
DATE 08 AUG 2017



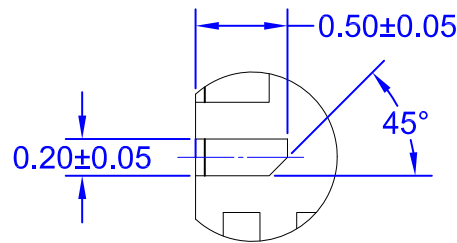
TOP VIEW



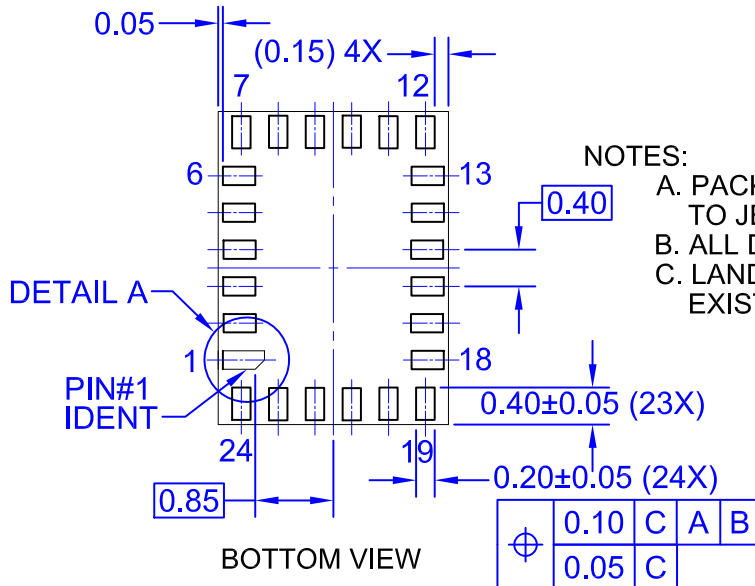
LAND PATTERN RECOMMENDATION



SIDE VIEW



DETAIL A  
SCALE 2:1



BOTTOM VIEW

**NOTES:**

- A. PACKAGE DOES NOT FULLY CONFORM TO JEDEC STANDARD
- B. ALL DIMENSIONS ARE IN MILLIMETERS
- C. LAND PATTERN RECOMMENDATION IS EXISTING INDUSTRY LAND PATTERN

⊕	0.10	C	A	B
	0.05	C		

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